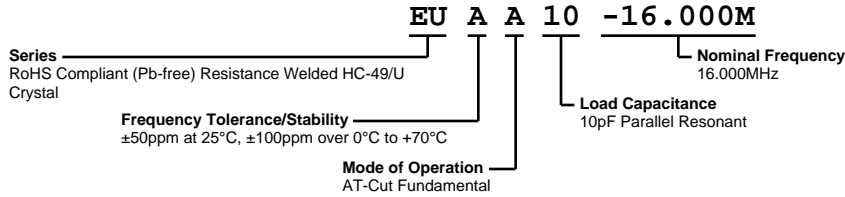


# EUAA10-16.000M



**ECLIPTEK**  
CORPORATION



## ELECTRICAL SPECIFICATIONS

Nominal Frequency	16.000MHz
Frequency Tolerance/Stability	$\pm 50\text{ppm}$ at 25°C, $\pm 100\text{ppm}$ over 0°C to +70°C
Aging at 25°C	$\pm 5\text{ppm/year}$ Maximum
Load Capacitance	10pF Parallel Resonant
Shunt Capacitance (C0)	7pF Maximum
Equivalent Series Resistance	25 Ohms Maximum
Mode of Operation	AT-Cut Fundamental
Drive Level	2mWatts Maximum
Storage Temperature Range	-40°C to +125°C
Insulation Resistance	500 Megaohms Minimum at 100Vdc

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Lead Integrity	MIL-STD-883, Method 2004
Lead Termination	Sn 2 $\mu\text{m}$ - 6 $\mu\text{m}$
Mechanical Shock	MIL-STD-202, Method 213, Condition C
Resistance to Soldering Heat	MIL-STD-202, Method 210
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010
Vibration	MIL-STD-883, Method 2007, Condition A

## MECHANICAL DIMENSIONS (all dimensions in millimeters)



LINE	MARKING
1	ECLIPTEK
2	E16.000M <i>E=Configuration Designator</i>
3	XX <i>XX=Ecliptek Manufacturing Code</i>

## Recommended Solder Reflow Methods



### High Temperature Solder Bath (Wave Solder)

<b><math>T_s</math> MAX to <math>T_L</math> (Ramp-up Rate)</b>	3°C/second Maximum
<b>Preheat</b>	
- Temperature Minimum ( $T_s$ MIN)	150°C
- Temperature Typical ( $T_s$ TYP)	175°C
- Temperature Maximum ( $T_s$ MAX)	200°C
- Time ( $t_s$ MIN)	60 - 180 Seconds
<b>Ramp-up Rate (<math>T_L</math> to <math>T_p</math>)</b>	3°C/second Maximum
<b>Time Maintained Above:</b>	
- Temperature ( $T_L$ )	217°C
- Time ( $t_L$ )	60 - 150 Seconds
<b>Peak Temperature (<math>T_p</math>)</b>	260°C Maximum for 10 Seconds Maximum
<b>Target Peak Temperature (<math>T_p</math> Target)</b>	250°C +0/-5°C
<b>Time within 5°C of actual peak (<math>t_p</math>)</b>	20 - 40 seconds
<b>Ramp-down Rate</b>	6°C/second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	8 minutes Maximum
<b>Moisture Sensitivity Level</b>	Level 1

## Recommended Solder Reflow Methods



### Low Temperature Solder Bath (Wave Solder)

$T_s \text{ MAX}$ to $T_L$ (Ramp-up Rate)	$5^\circ\text{C/second}$ Maximum
<b>Preheat</b>	
- Temperature Minimum ( $T_s \text{ MIN}$ )	N/A
- Temperature Typical ( $T_s \text{ TYP}$ )	$150^\circ\text{C}$
- Temperature Maximum ( $T_s \text{ MAX}$ )	N/A
- Time ( $t_s \text{ MIN}$ )	30 - 60 Seconds
<b>Ramp-up Rate (<math>T_L</math> to <math>T_p</math>)</b>	$5^\circ\text{C/second}$ Maximum
<b>Time Maintained Above:</b>	
- Temperature ( $T_L$ )	$150^\circ\text{C}$
- Time ( $t_L$ )	200 Seconds Maximum
<b>Peak Temperature (<math>T_p</math>)</b>	$245^\circ\text{C}$ Maximum
<b>Target Peak Temperature (<math>T_p \text{ Target}</math>)</b>	$245^\circ\text{C}$ Maximum 1 Time / $235^\circ\text{C}$ Maximum 2 Times
<b>Time within <math>5^\circ\text{C}</math> of actual peak (<math>t_p</math>)</b>	5 seconds Maximum 1 Time / 15 seconds Maximum 2 Times
<b>Ramp-down Rate</b>	$5^\circ\text{C/second}$ Maximum
<b>Time <math>25^\circ\text{C}</math> to Peak Temperature (t)</b>	N/A
<b>Moisture Sensitivity Level</b>	Level 1

### Low Temperature Manual Soldering

$185^\circ\text{C}$  Maximum for 10 seconds Maximum, 2 times Maximum.

### High Temperature Manual Soldering

$260^\circ\text{C}$  Maximum for 5 seconds Maximum, 2 times Maximum.